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FGL40N120AND 1200V NPT IGBT

Features

· High speed switching

• Low saturation voltage : $V_{CE(sat)} = 2.6 \text{ V} @ I_C = 40 \text{A}$

· High input impedance

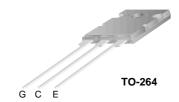
• CO-PAK, IGBT with FRD : $t_{rr} = 75$ ns (typ.)

Applications

Induction Heating, UPS, AC & DC motor controls and general purpose inverters.

Description

Employing NPT technology, Fairchild's AND series of IGBTs provides low conduction and switching losses. The AND series offers an solution for application such as induction heating (IH), motor control, general purpose inverters and uninterruptible power supplies (UPS).





Absolute Maximum Ratings

| Symbol | Parameter | | FGL40N120AND | Units |
|--------------------|--|-------------------------|--------------|-------|
| V _{CES} | Collector-Emitter Voltage | | 1200 | V |
| V_{GES} | Gate-Emitter Voltage | | ±25 | V |
| | Collector Current | @T _C = 25°C | 64 | Α |
| IC | Collector Current | @T _C = 100°C | 40 | Α |
| I _{CM(1)} | Pulsed Collector Current | | 160 | Α |
| I _F | Diode Continuous Forward Current @T _C = 100°C | | 40 | Α |
| I _{FM} | Diode Maximum Forward Current | | 240 | Α |
| D | Maximum Power Dissipation | @T _C = 25°C | 500 | W |
| P_{D} | Maximum Power Dissipation | @T _C = 100°C | 200 | W |
| SCWT | Short Circuit Withstand Time, V _{CE} = 600V, V _{GE} = 15V, T _C = 125°C | | 10 | μs |
| TJ | Operating Junction Temperature | | -55 to +150 | °C |
| T _{STG} | Storage Temperature Range | | -55 to +150 | °C |
| T _L | Maximum Lead Temp. for Soldering Purposes, 1/8" from Case for 5 seconds | | 300 | °C |

Notes:

(1) Pulse width limited by max. junction temperature

Thermal Characteristics

| Symbol | Parameter | Тур. | Max. | Units |
|------------------------|---|------|------|-------|
| $R_{\theta JC}$ (IGBT) | Thermal Resistance, Junction-to-Case | | 0.25 | °C/W |
| $R_{\theta JC}(DIODE)$ | Thermal Resistance, Junction-to-Case | | 0.7 | °C/W |
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient | | 25 | °C/W |

Package Marking and Ordering Information

| Device Marking | Device | Package | Reel Size | Tape Width | Quantity |
|-----------------------|--------------|---------|-----------|------------|----------|
| FGL40N120AND | FGL40N120AND | TO-264 | = | - | 25 |

Electrical Characteristics of the IGBT $T_C = 25^{\circ}C$ unless otherwise noted

| Symbol | Parameter | Conditions | Min. | Тур. | Max. | Units |
|--|--|--|------|------|------|-------|
| Off Charact | eristics | | | | | |
| BV _{CES} | Collector-Emitter Breakdown Voltage | $V_{GE} = 0V$, $I_C = 1mA$ | 1200 | | | V |
| BV _{CES} / ΔT _J | Temperature Coefficient of Breakdown Voltage | V _{GE} = 0V, I _C = 1mA | | 0.6 | | V/°C |
| I _{CES} | Collector Cut-Off Current | $V_{CE} = V_{CES}, V_{GE} = 0V$ | | | 1 | mA |
| I _{GES} | G-E Leakage Current | $V_{GE} = V_{GES}, V_{CE} = 0V$ | | | ±250 | nA |
| On Charact | eristics | | | | | |
| V _{GE(th)} | G-E Threshold Voltage | $I_{C} = 250 \mu A, V_{CE} = V_{GE}$ | 3.5 | 5.5 | 7.5 | V |
| - GE(III) | | I _C = 40A, V _{GE} = 15V | | 2.6 | 3.2 | V |
| V _{CE(sat)} | Collector to Emitter Saturation Voltage | I _C = 40A, V _{GE} = 15V, T _C = 125°C | | 2.9 | | V |
| | | I _C = 64A, V _{GE} = 15V | | 3.15 | | V |
| Dynamic Cl | haracteristics | | | l . | | 1 |
| C _{ies} | Input Capacitance | | | 3200 | | pF |
| C _{oes} | Output Capacitance | $V_{CE} = 30V, V_{GE} = 0V$ | | 370 | | pF |
| C _{res} | Reverse Transfer Capacitance | f = 1MHz | | 125 | | pF |
| Switching (| Characteristics | | | | | |
| t _{d(on)} | Turn-On Delay Time | | | 15 | | ns |
| t _r | Rise Time |] | | 20 | | ns |
| t _{d(off)} | Turn-Off Delay Time | $V_{CC} = 600V, I_{C} = 40A,$ | | 110 | | ns |
| t _f | Fall Time | $R_G = 5\Omega, V_{GE} = 15V,$ | | 40 | 80 | ns |
| E _{on} | Turn-On Switching Loss | Inductive Load, T _C = 25°C | | 2.3 | 3.45 | mJ |
| E _{off} | Turn-Off Switching Loss | | | 1.1 | 1.65 | mJ |
| E _{ts} | Total Switching Loss | | | 3.4 | 5.1 | mJ |
| t _{d(on)} | Turn-On Delay Time | | | 20 | | ns |
| t _r | Rise Time | | | 25 | | ns |
| t _{d(off)} | Turn-Off Delay Time | $V_{CC} = 600V, I_{C} = 40A,$ | | 120 | | ns |
| t _f | Fall Time | $R_G = 5\Omega$, $V_{GE} = 15V$, | | 45 | | ns |
| E _{on} | Turn-On Switching Loss | Inductive Load, T _C = 125°C | | 2.5 | | mJ |
| E _{off} | Turn-Off Switching Loss | | | 1.8 | | mJ |
| E _{ts} | Total Switching Loss | | | 4.3 | | mJ |
| Qg | Total Gate charge | | | 220 | 330 | nC |
| Q _{ge} | Gate-Emitter Charge | $V_{CE} = 600V, I_{C} = 40A,$ $V_{GE} = 15V$ | | 25 | 38 | nC |
| Q _{gc} | Gate-Collector Charge | 1 *GE = 10 * | | 130 | 195 | nC |

Electrical Characteristics of DIODE $T_C = 25^{\circ}C$ unless otherwise noted

| Symbol | Parameter | Test Conditions | | Min. | Тур. | Max. | Units |
|-----------------|-------------------------------|-----------------------|------------------------|------|------|------|-------|
| V | Diode Forward Voltage | I _F = 40A | T _C = 25°C | | 3.2 | 4.0 | V |
| V_{FM} | | | T _C = 125°C | | 2.7 | | V |
| + | Diode Reverse Recovery Time | | T _C = 25°C | | 75 | 112 | nS |
| t _{rr} | Diode Reverse Recovery Time | | T _C = 125°C | | 130 | | 113 |
| | Diode Peak Reverse Recovery | I _F = 40A, | T _C = 25°C | | 8 | 12 | Α |
| l rr | Current | | T _C = 125°C | | 13 | | _ ^ |
| Q _{rr} | Diode Reverse Recovery Charge | | T _C = 25°C | | 300 | 450 | nC |
| | | | T _C = 125°C | | 845 | | iiC |

Typical Performance Characteristics

Figure 1. Typical Output Characteristics

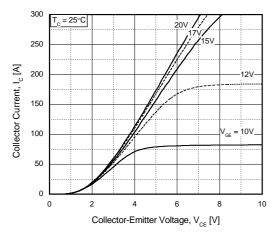


Figure 3. Saturation Voltage vs. Case
Temperature at Variant Current Level

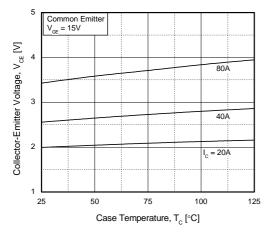


Figure 5. Saturation Voltage vs. V_{GE}

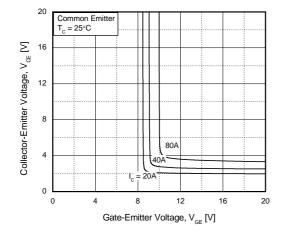


Figure 2. Typical Saturation Voltage Characteristics

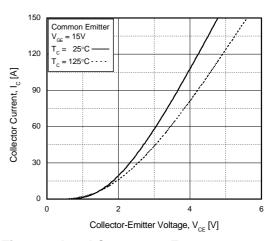


Figure 4. Load Current vs. Frequency

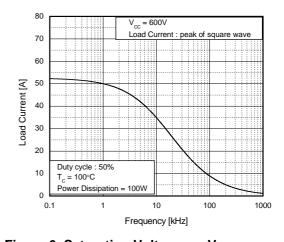
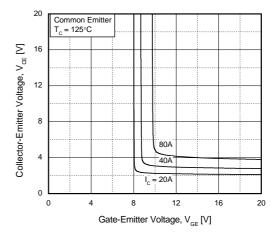


Figure 6. Saturation Voltage vs. V_{GE}



Typical Performance Characteristics (Continued)

Figure 7. Capacitance Characteristics

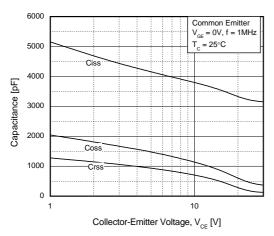


Figure 9. Turn-Off Characteristics vs. **Gate Resistance**

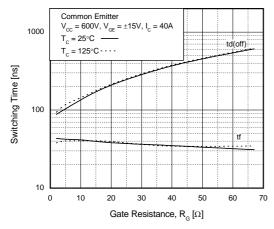


Figure 11. Turn-On Characteristics vs. **Collector Current**

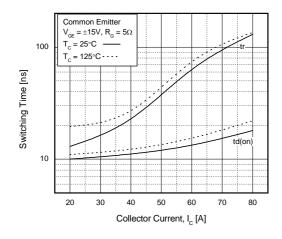


Figure 8. Turn-On Characteristics vs. Gate Resistance

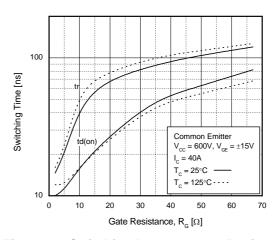


Figure 10. Switching Loss vs. Gate Resistance

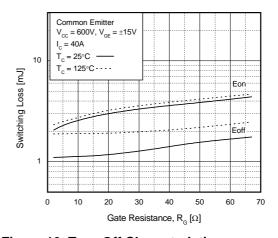
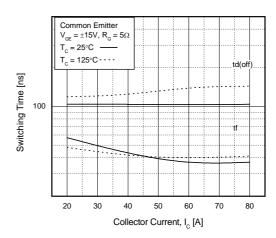


Figure 12. Turn-Off Characteristics vs. **Collector Current**



Typical Performance Characteristics (Continued)

Figure 13. Switching Loss vs. Collector Current

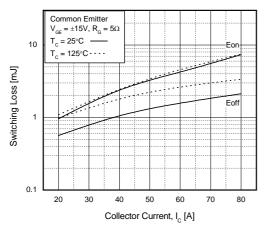


Figure 15. SOA Characteristics

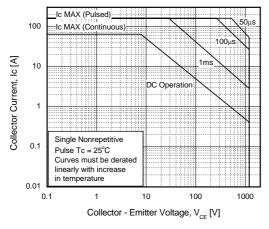


Figure 17. Forward Characteristics

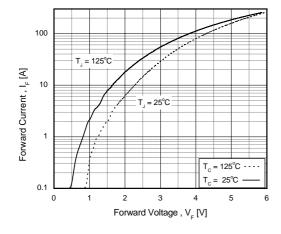


Figure 14. Gate Charge Characteristics

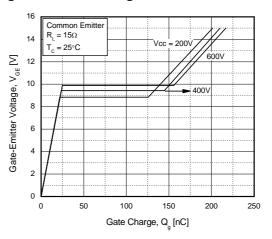


Figure 16. Turn-Off SOA

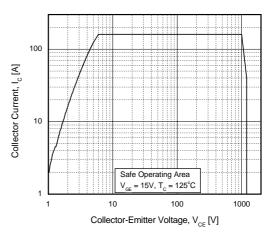
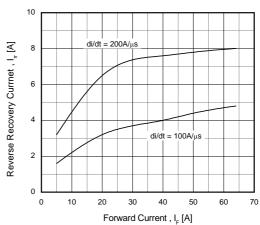


Figure 18. Reverse Recovery Current



Typical Performance Characteristics (Continued)

Figure 19. Stored Charge

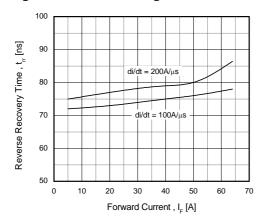


Figure 20. Reverse Recovery Time

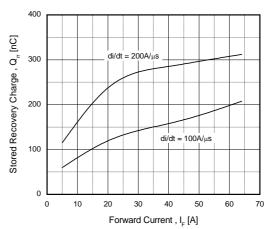
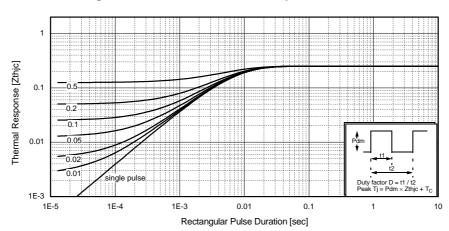
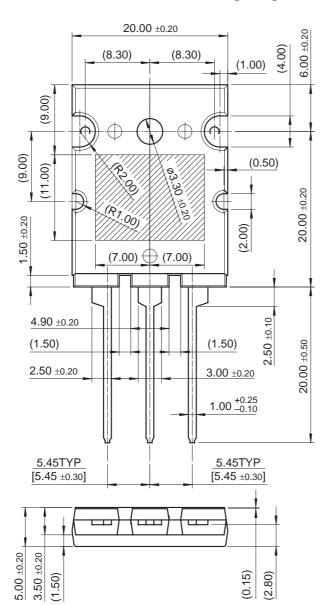


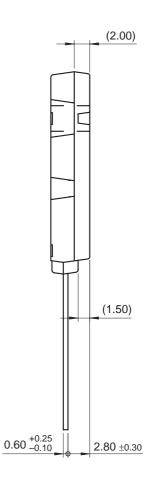
Figure 21. Transient Thermal Impedance of IGBT



Mechanical Dimensions

TO-264





Dimensions in Millimeters





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